

WHAT IS CLAIMED IS:

sub B1
09986005-110701

1. A resin molded component, comprising metal coating treatment being provided on the surface by a physical deposition method chosen from among sputtering, vacuum deposition, and ion plating after the surface is activated by plasma treatment, and characterized in that the resin molded component is produced by forming a resin composition combined a base resin comprising of a thermoplastic resin or a thermosetting resin with a rubber-like elastic material.

2. The resin molded component according to claim 1 characterized in that at least one kind of copolymer chosen from ethylene-glycidyl methacrylate-methyl acrylate copolymer, ethylene-maleic anhydride-ethyl acrylate copolymer, graft copolymer of ethylene-glycidyl methacrylate copolymer and acrylonitrile-styrene copolymer, and ethylene-glycidyl methacrylate-ethylene-ethyl acrylate copolymer is used as said rubber-like elastic material.

sub B2
3. The resin molded component according to claim 1 characterized in that a mixing amount of said rubber-like elastic material is from 0.5 to 10 parts in mass to 100 parts in mass of said base resin.

4. The resin molded component according to claim 1 characterized in that polyphthalamide or polyphenylene sulfide is used as said base resin.

5. The resin molded component according to claim 1 characterized in that said resin composition is a composition compounded with an inorganic filler.

Sub
B2
completd

6. The resin molded component according to claim 5 characterized in that said inorganic filler is fibrous of 0.5 to 5 μm in diameter and 10 to 50 μm in length.

7. The resin molded component according to claim 5 characterized in that said inorganic filler is plate-form.

8. The resin molded component according to claim 5 characterized in that said inorganic filler in a fiber form of 0.5 to 5 μm in diameter and 10 to 50 μm in length and the plate-form inorganic filler are used in combination.

9. The resin molded component according to claim 5 characterized in that said inorganic filler is spherical.

10. The resin molded component according to claim 5 characterized in that a mixing amount of said inorganic filler is from 40 to 75% in mass with respect to said whole resin composition.

11. The resin molded component according to claim 1 characterized by being used for printed circuit boards.

09986005-110701

Add
B2